

ABSTRACT OF THE DISCLOSURE

An adaptable pin assembly for a BGA based IC encapsulation is disclosed. The pin assembly comprises an upper cover comprising a plurality of longitudinal channels arranged in rows and columns for anchoring portions of a plurality of longitudinal, conductive, detachable, and resilient pins; and a lower cover coupled to the upper cover, the lower cover comprising a plurality of longitudinal channels arranged in rows and columns for anchoring the remaining portions of the pins. In testing an encapsulated IC chip the pin assembly is sandwiched between the IC chip having a plurality of bottom tin balls and a circuit board of an IC test device, the tin balls are rested on the upper pins, and the circuit board is connected to the lower pins so as to form an electrical connection between the tin balls and the circuit board.